

# The 10th International Conference on Integrated Circuits and Microsystems

October 17-19, 2025 | Hefei, China

[www.icicm.net](http://www.icicm.net)



2025 The 10th International Conference on Integrated Circuits and Microsystems (ICICM 2025) will be held in Hefei, China on October 17-19, 2025, which is co-sponsored by Anhui University; Southeast University and University of Electronic Science and Technology of China.

## Invited Speakers Recruitment

- ICICM 2025 recruit domestic and international invited speakers in the Integrated Circuits and Microsystems field.
- ICICM 2025 will assign the selected presentations to relevant forums. Applicants are requested to send their resumes, academic achievements, speech title and abstract, and two-inch photo as attachments to [icicm\\_conf@vip.163.com](mailto:icicm_conf@vip.163.com).
- Invited speakers are required to share best practices and research results, and are not allowed to promote any products or services during the speech.

## Topics

Include but not limited

- Track 1: Electronic Design Automation (EDA)**
  - Progress of EDA algorithms
  - EDA for emerging technologies
  - Hardware-software co-design with EDA
  - EDA in High Performance Computing (HPC)
  - EDA in analog and mixed-signal design
- Track 2: Integrated Circuit and System Design**
  - Digital, analog, mixed-signal IC and SOC design technology
  - IC computer-aided design technology, DFM
  - Modeling and simulation
- Track 3: Semiconductor Devices and Circuits**
  - Components and circuits for wireless systems
  - Low power, RF devices and circuits
  - Silicon/Germanium Devices and Device Physics
  - Compound semiconductor devices and circuits
- Track 4: Process Technology and Manufacturing**
  - Silicon integrated circuits and manufacturing
  - Interconnect, low-K, high-K and other process technologies
  - Packaging and testing technology, equipment technology

For more topics, please visit at: <http://icicm.net/call-for-papers.html>

### Track Recruitment

If you are willing to organize one or more tracks, please contact us to get more details. All papers in track will also be included in the conference proceedings and indexed by EI Compendex and Scopus.

## Submission

- Full paper (Presentation & Publication)
  - Abstract (Presentation only)
- Submission Link:  
<https://easychair.org/conferences/?conf=icicm2025>  
Email submission: [icicm\\_conf@vip.163.com](mailto:icicm_conf@vip.163.com)  
Full paper template (Word): <http://icicm.net/files/Template.doc>  
Full paper template (Latex):  
<http://icicm.net/files/IEEE-conference-proceeding-Latex.rar>

## Publication

Submitted papers will be Peer-Reviewed (Double Blind) and the accepted ones will be collected in the conference proceedings and indexed by EI Compendex and Scopus, etc.

\*\*Proceedings of ICICM2016-2024 have been successfully include in IEEE Xplore and indexed by EI Compendex and Scopus already!

## Conference History

Year	City	IEEE	ISBN
ICICM2016	Chengdu	IEEE	ISBN: 978-1-5090-2814-6
ICICM2017	Nanjing	IEEE	ISBN: 978-1-5386-3506-3
ICICM2018	Shanghai	IEEE	ISBN: 978-1-5386-8311-8
ICICM2019	Beijing	IEEE	ISBN: 978-1-7281-5132-8
ICICM2020	Nanjing	IEEE	ISBN: 978-1-7281-8978-9
ICICM2021	Nanjing	IEEE	ISBN: 978-1-6654-5886-3
ICICM2022	Xi'an	IEEE	ISBN: 978-1-6654-6042-2
ICICM2023	Nanjing	IEEE	ISBN: 979-8-3503-1849-4
ICICM2024	Wuhan	IEEE	ISBN: 979-8-3315-0944-6

## Important Dates

Submission Deadline	Notification Deadline	Registration Deadline
April 1, 2025	April 30, 2025	May 15, 2025

## Organizing Committee

- Advisory Chairs**
  - Junfa Mao, Shenzhen University, China
  - Yue Hao, Xidian University, China
- Conference Chairs**
  - Zhigong Wang, Southeast University, China
  - Xiulong Wu, Anhui University, China
  - Kaixue Ma, Tianjin University, China (IEEE FELLOW)
- Conference Co-Chairs**
  - Ning Xu, Wuhan University of Technology, China
  - Xiaoqing Wen, Kyushu Institute of Technology, Japan (IEEE FELLOW)
  - Qiang Li, University of Electronic Science and Technology of China, China
- Program Chairs**
  - Jiliang Zhang, Hunan University, China
  - Ying Wang, Institute of Computing Technology, Chinese Academy of Sciences, China
  - Meng Zhang, Southeast University, China
  - Sheng Chang, Wuhan University, China
  - Yingmei Chen, Southeast University, China
  - Zhikuang Cai, Nanjing University of Posts and Telecommunications, China
  - Zhuo Zou, Fudan University, China
  - Jianguo Hu, Sun Yat-sen University, China
  - Bei Yu, The Chinese University of Hong Kong, China
- Program Co-Chairs**
  - Junyong Deng, Xi'an University of Posts & Telecommunications, China
  - Jun Xu, Nanjing University, China
  - Zhixiong Di, Southwest Jiaotong University, China
  - Guojie Luo, Peking University, China
  - Xiaojun Zhai, University of Essex, UK
  - Wei Xing, The University of Sheffield, UK
- Program Committee**
  - Shi Pu, Wuhan University of Technology, China
  - Haizhi Song, University Of Electronic Science And Technology Of China, China
  - Lu Zhu, Sun Yat-sen University, China
  - Youming Zhang, Southeast University, China
  - Jianshi Tang, Tsinghua University, China
  - Weiguang Sheng, Shanghai Jiao Tong University, China
  - Hao Gao, Austria & Eindhoven University of Technology, The Netherlands
  - Yun Fang, Silicon Austria Labs, Austria
  - Jeff Kilby, Auckland University of Technology, New Zealand
  - Zhijun Zhou, Southeast University, China
  - Xingyuan Tong, Xi'an University Of Posts & Telecommunications, China
  - Wei Hu, Northwestern Polytechnical University, China
- Local Chair**
  - Lin Cheng University of Science and Technology of China
- Publication Chairs**
  - Xinyu Zhao, Zhejiang University, China
  - Qiang Wu, Beijing CAS Industrial Energy and Environment Technology Institute, China
- Student Program Chairs**
  - Keping Wang, Tianjin University, China
  - Delong Shang, Institute of Microelectronics of the Chinese Academy of Sciences, China
  - Fanyi Meng, Tianjin University, China
- Student Program Committee**
  - Li Du, Nanjing University, China
  - Lei Wang, Nanjing University of Posts And Telecommunications, China
  - Xianbo Li, Sun Yat-sen University, China
  - Tiehu Li, Chongqing University of Technology, China
  - Moufu Kong, University of Electronic Science and Technology of China, China
  - Jiaxin Liu, University of Electronic Science and Technology of China, China
  - Maliang Liu, Xidian University, China

Co-Sponsored by: Hosted by: Patrons:



Media Support:



Conference Secretary: Ms. Mila Xiao

Email: [icicm\\_conf@vip.163.com](mailto:icicm_conf@vip.163.com)

Tel: (86)134-0855-5552

Contact Us